

## PATENT ASSIGNMENT COVER SHEET

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<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
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YASUTOSHI AIBARA	02/14/2002
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<b>Property Type</b>	<b>Number</b>
Patent Number:	7122775
Patent Number:	6841770
Patent Number:	7351946
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<b>NAME OF SUBMITTER:</b>	JOHN R. MATTINGLY
<b>SIGNATURE:</b>	/John R. Mattingly/
<b>DATE SIGNED:</b>	05/11/2017
<b>Total Attachments: 1</b> source=(I) Assignment - Inv to HitLtd and ULSI and Tohbu#page1.tif	

# ASSIGNMENT

( 譲 渡 証 )

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by HITACHI, LTD., Hitachi ULSI Systems Co., Ltd. and Hitachi Tohbu Semiconductor, Ltd., corporations organized under the laws of Japan, located at 6, Kanda Surugadai 4-chome, Chiyoda-ku, Tokyo, Japan ; 22-1, Josuihoncho 5-chome, Kodaira-shi, Tokyo, Japan and 1-1, Nishiyokotemachi, Takasaki-shi, Gunma, Japan, respectively, receipt of which is hereby acknowledged I do hereby sell and assign to said HITACHI, LTD., Hitachi ULSI Systems Co., Ltd. and Hitachi Tohbu Semiconductor, Ltd., their successors and assigns, all my right, title and interest, in and for the United States of America, in and to

## SEMICONDUCTOR INTEGRATED CIRCUIT DEVICE AND IMAGING SYSTEM

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire owner ship of the said Letters Patent when granted, to be held and enjoyed by said HITACHI, LTD., Hitachi ULSI Systems Co., Ltd. and Hitachi Tohbu Semiconductor, Ltd., their successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted, as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said HITACHI, LTD., Hitachi ULSI Systems Co., Ltd. and Hitachi Tohbu Semiconductor, Ltd.

Signed on the date(s) indicated aside signatures:

INVENTOR(S)

(発明者フルネームサイン)

Date Signed

(署名日)

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9) _____	_____
10) _____	_____

PATENT

RECORDED: 02/25/2002  
RECORDED: 03/12/2017

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